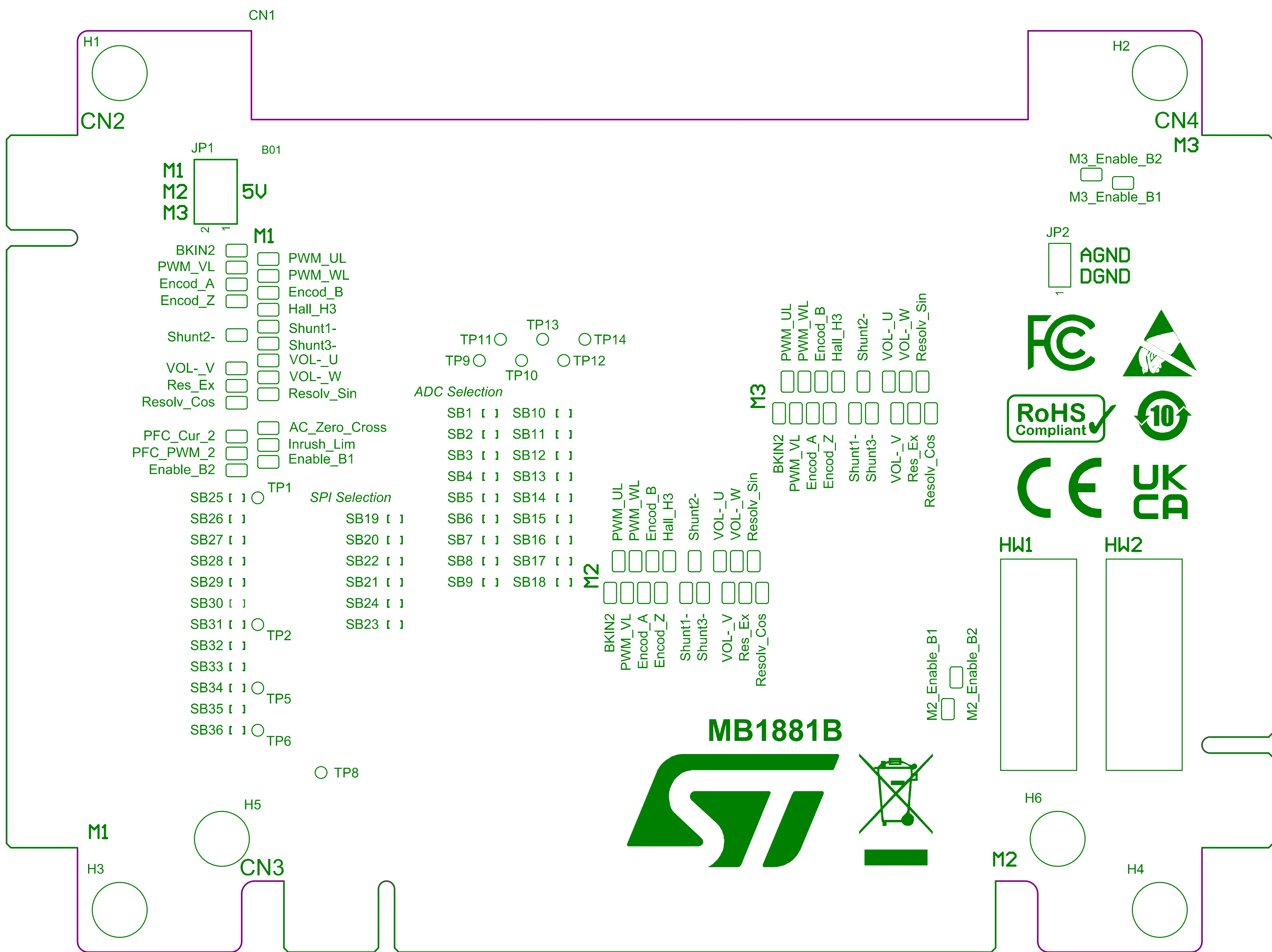
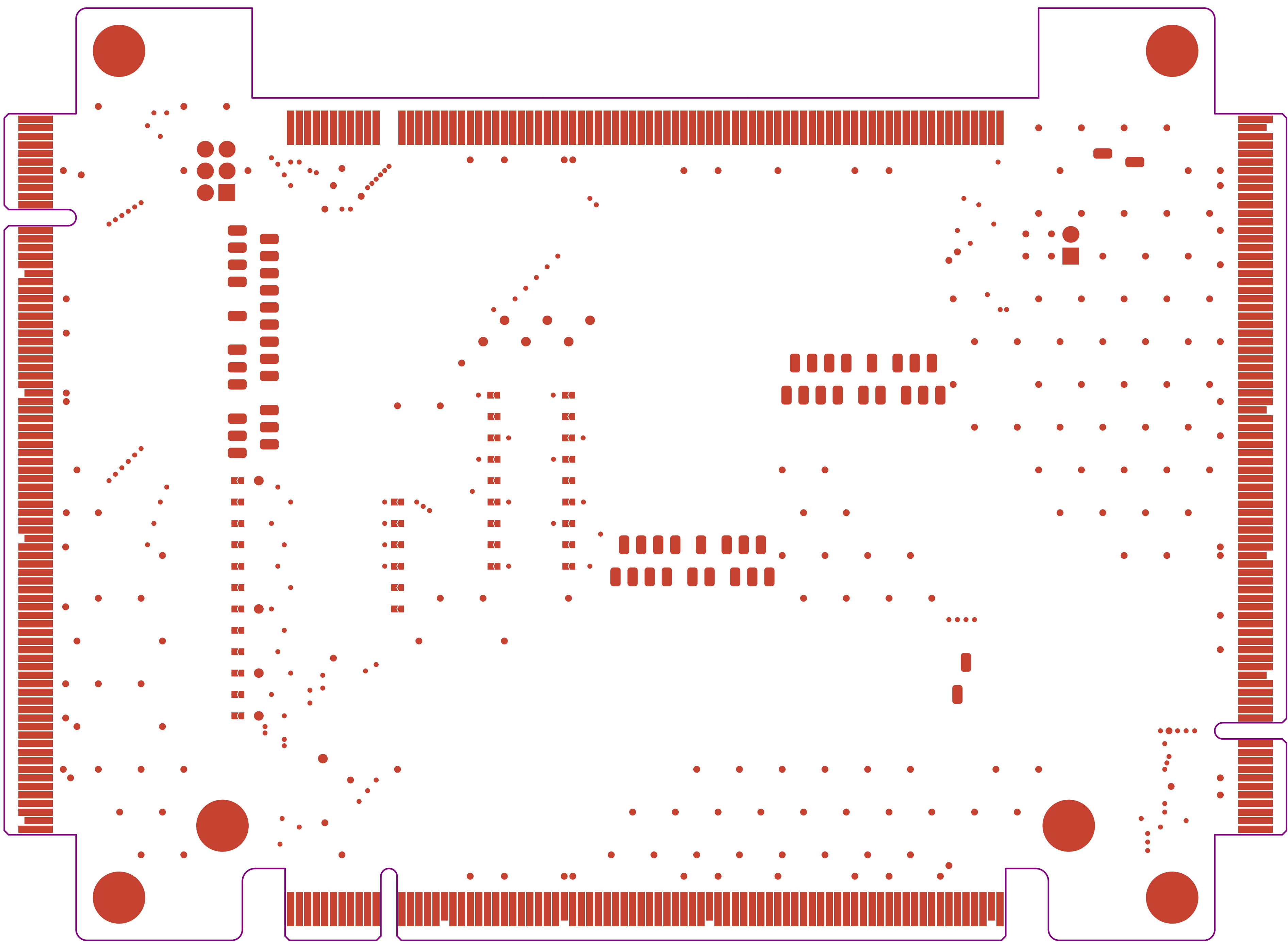
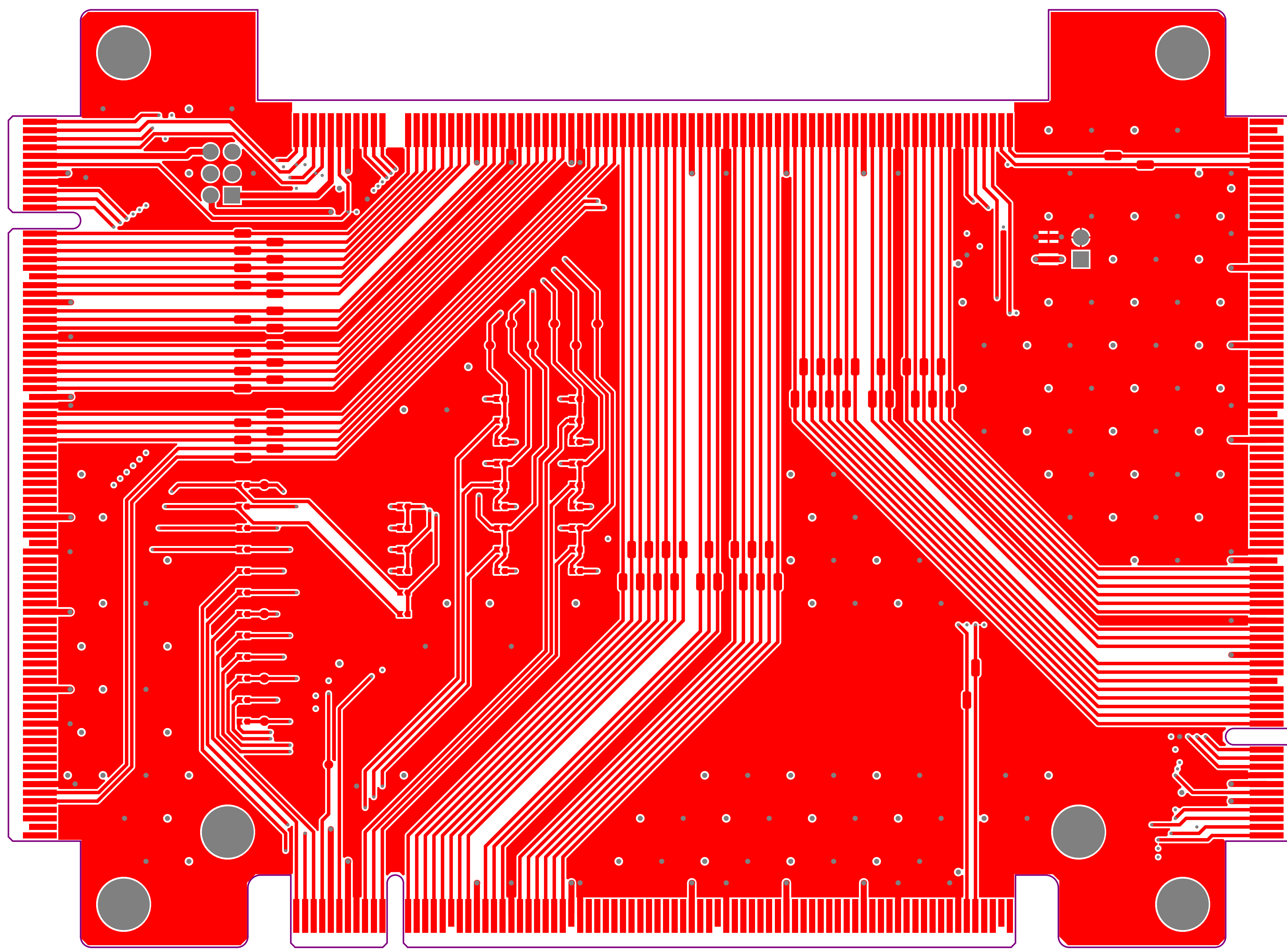
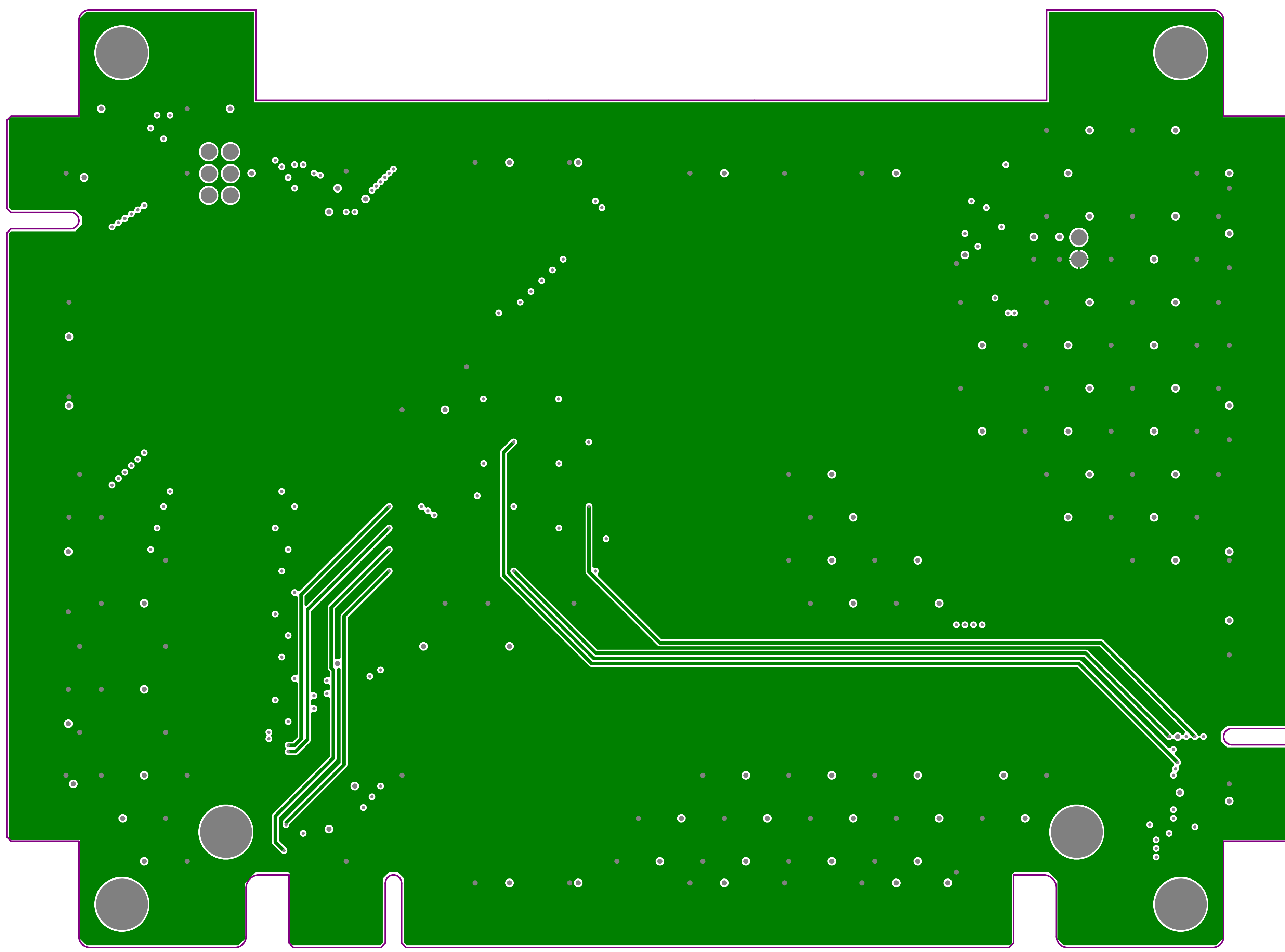
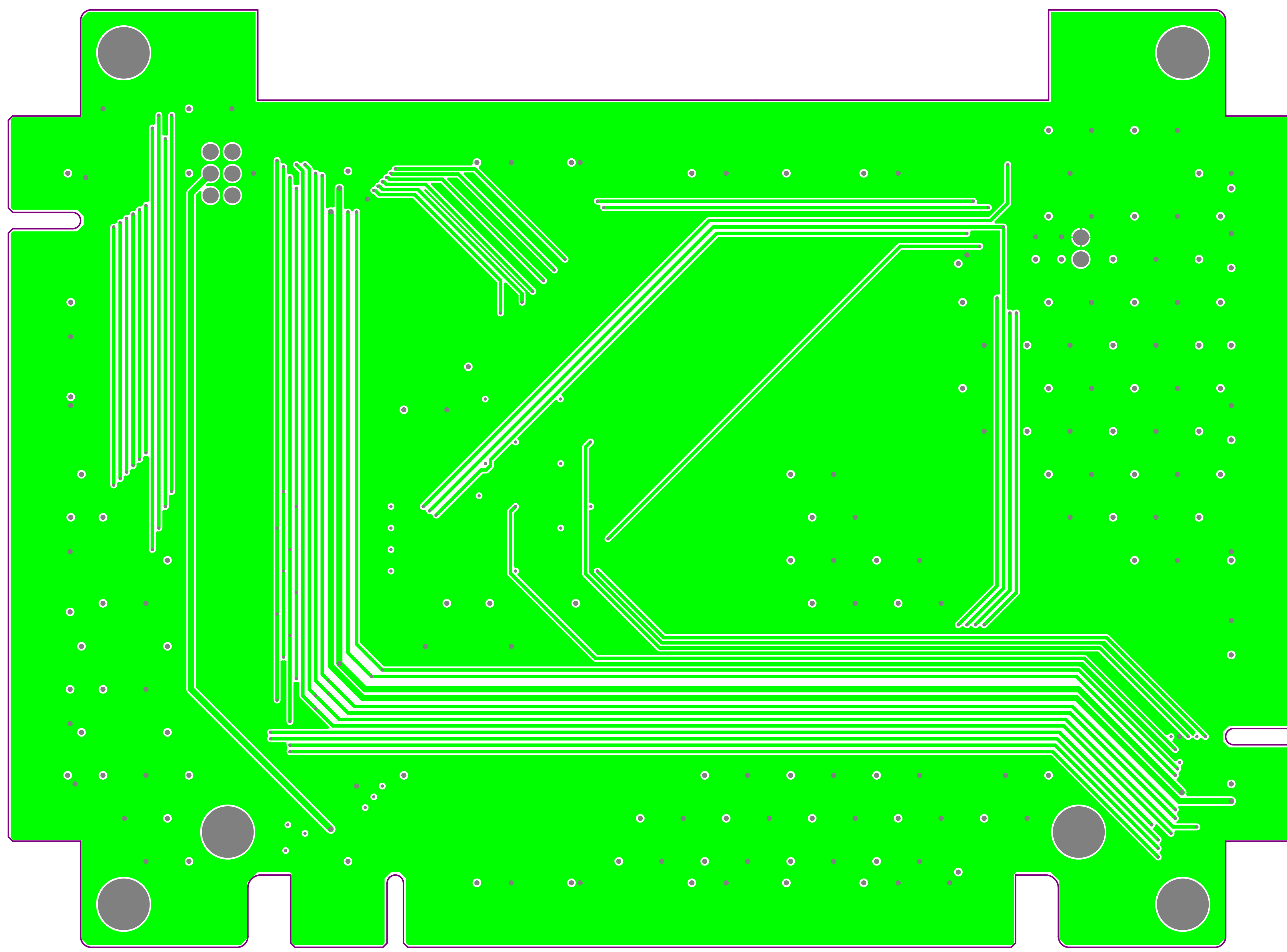


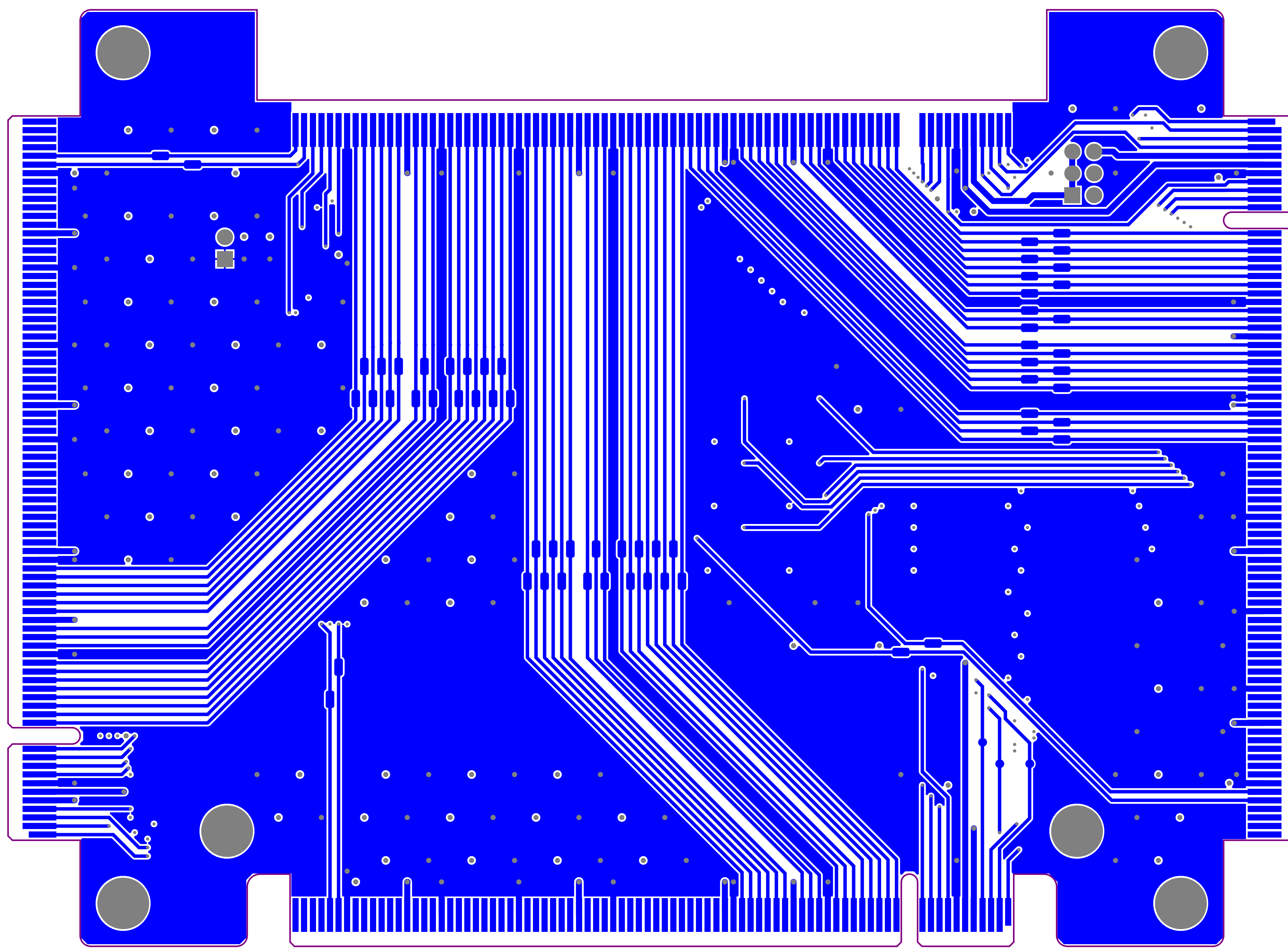


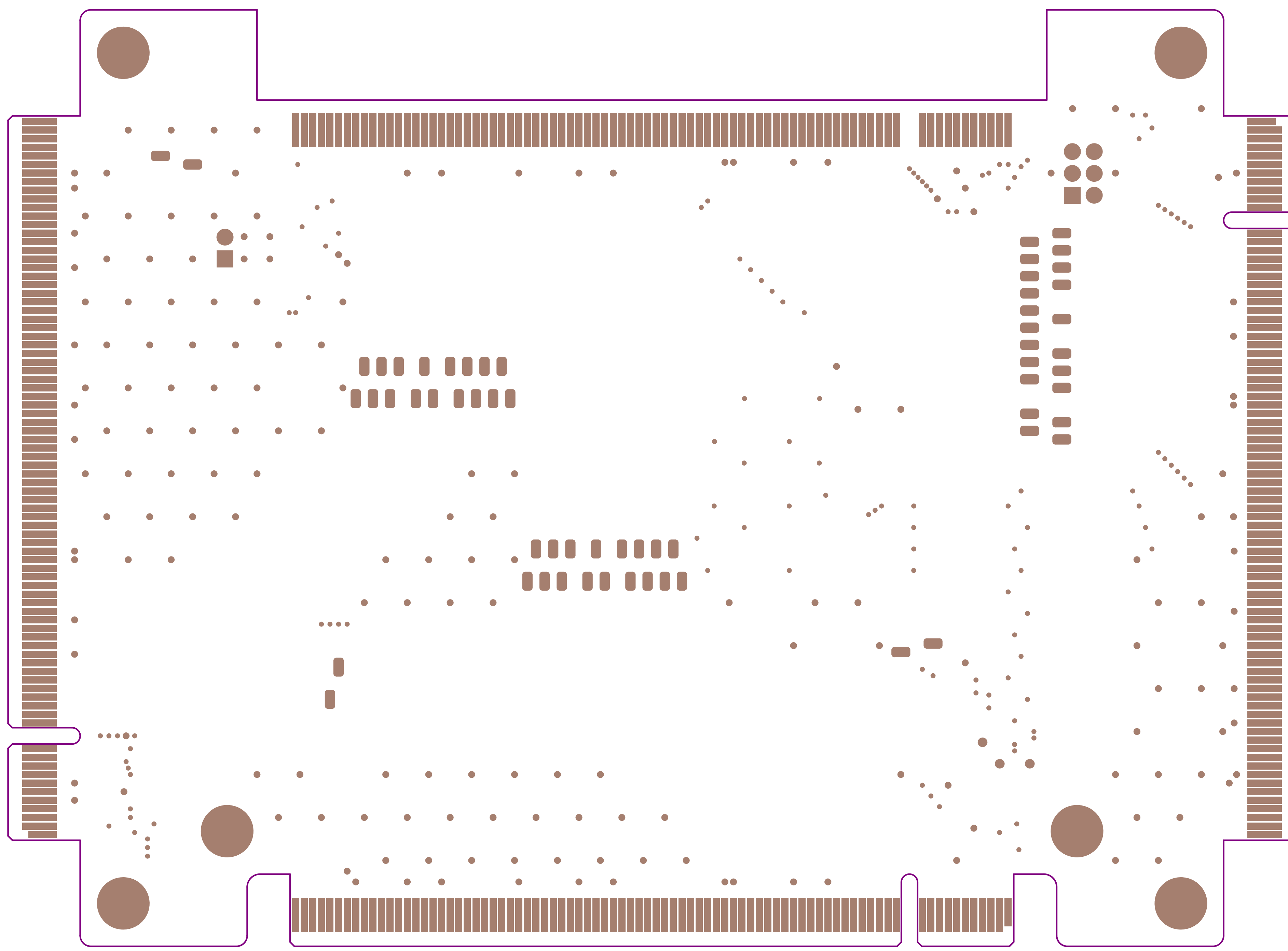


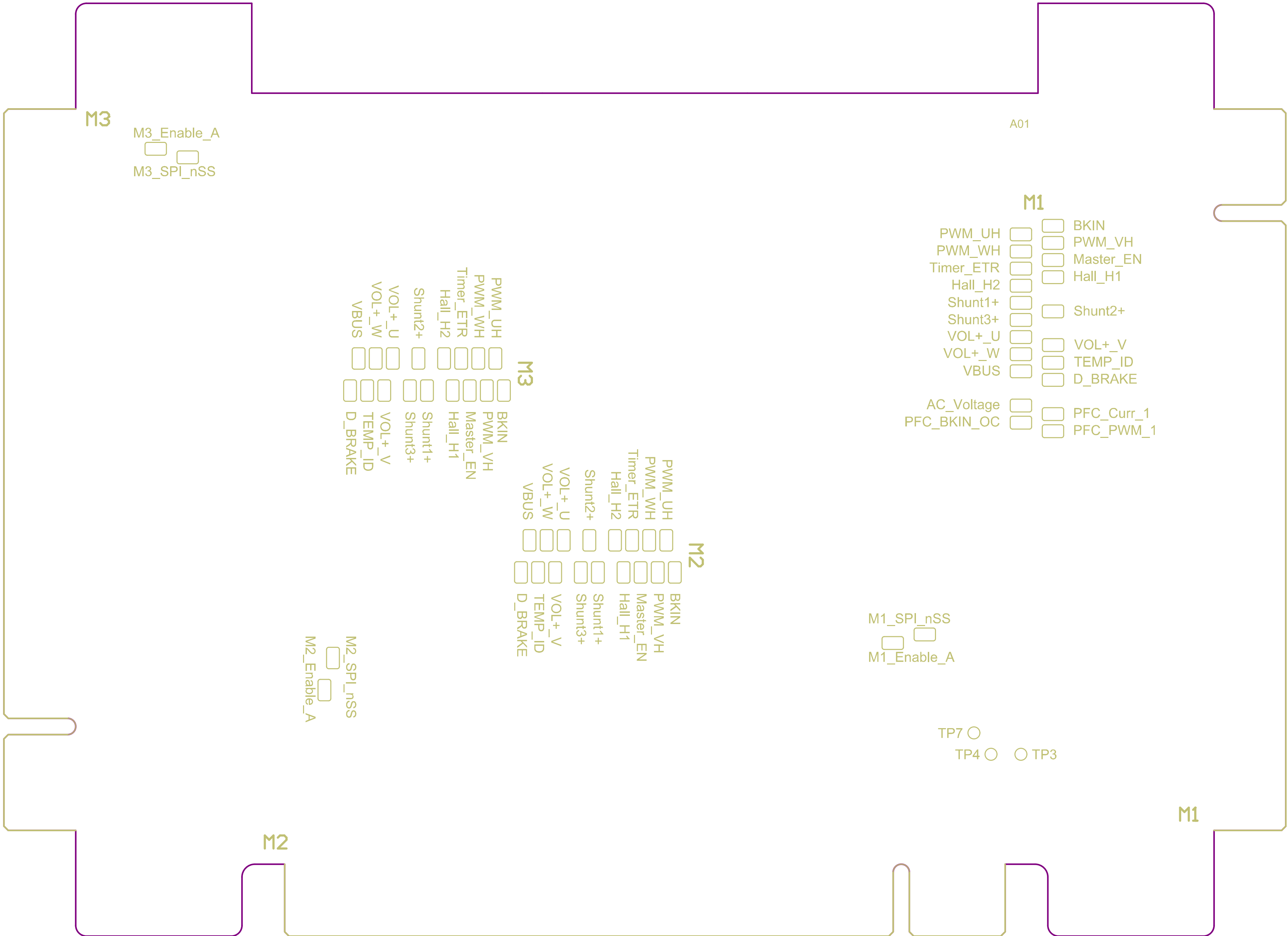












PCB SPECIFICATIONS :

A. MATERIAL :

FR-4

☐ TG-170

☒ TG-150

☐ TG-140

B. MATERIAL FAMILY :

N/A

C. SOLDERMASK COLOR :

☐ GREEN

☒ BLUE

☐ RED

☐ BLACK

D. SILKSCREEN COLOR :

☒ WHITE

☐ YELLOW

☐ BLACK

E. SURFACE FINISH :

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

F. IMPEDANCE CONTROL :

☒ NO

☐ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

G. THROUGH VIA :

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

PLUG MATERIAL : ☒ SOLDERMASK

☐ NON-CONDUCTIVE EPOXY.

H. STACK-UP :

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)
⊕	121	8,00mil (0,20mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v38h20			
○	181	11,81mil (0,30mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v60h30			
□	8	39,37mil (1,00mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)			
☆	6	137,79mil (3,50mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c600h350m605			
	316 Total										

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0,59mil	3,5	
1	Top Layer	Copper	1,38mil		
	Dielectric 2	PP-006	2,80mil	4,1	
2	Layer 1	Copper	1,38mil		
	Dielectric 1	FR-4	59,06mil	4,8	
3	Layer 2	Copper	1,38mil		
	Dielectric 3	PP-006	2,80mil	4,1	
4	Bottom Layer	Copper	1,38mil		
	Bottom Solder	Solder Resist	0,59mil	3,5	
	Bottom Overlay				

